Atty. Docket No. CPAC 1029-3
Appl. No. 10/681,735

PATENT

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PATENT & TRADEMARK OFFICE

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: Marcos Karnezos

Application No.: 10/681,735

Filed: October 8, 2003

Title: **Semiconductor multi-package module having inverted land grid array (LGA) package stacked over ball grid array (BGA) package**

Examiner: Alonzo Chambliss

Group Art Unit: 2814

Date: November 4, 2005.

CERTIFICATE OF MAILING

I hereby certify that this correspondence is being deposited with the U.S. Postal Service with sufficient postage as first class mail in an envelope addressed to: MS Amendment, Commissioner of Patents, P.O. Box 1450, Alexandria, VA 22313-1450 on, November 4, 2005.

Signed _____
Bill Kennedy

COMMISSIONER FOR PATENTS
P.O. BOX 1450
Alexandria, VA 22313-1450

AMENDMENT

Dear Sir:

In response to the Office action mailed August 4, 2005, kindly amend the application as follows.

Amendments to the Specification begin on page 2 of this paper.

There are no amendments to the claims. A **Listing of Claims** is provided for the Examiner's convenience, beginning on page 3 of this paper.

Remarks begin on page 5 of this paper.